

850 Desktop Reflow Oven



Versatile Hot Air Convection Oven

A high level of functionality and control make the Model 850 lead-free reflow soldering oven an ideal choice for low-volume or prototyping.

Higher volume manufacturers can qualify materials and process windows without tying up production equipment, while low volume assemblers, schools and laboratories can use the Model 850 for pilot runs, prototyping and training.

Model 850 provides nearly all the essential tools needed to do some fairly advanced process development and experimentation in a low-cost bench-top system. It can also be used to "hot bake" moisture-sensitive devices prior to assembly, to eliminate the risk of moisture-related defects like popcorning.

Easy Control & Monitoring

Preheat- and reflow-phase time and temperature settings, controllable through an LCD touchscreen display, allow the Model 850 to attain a wide variety of thermal profiles for a broad assortment of reflow soldering, curing, and drying applications.

Built-in thermocouple, easy-read display, and large double-pane glass window allow the operator to fully monitor the entire process.

Compact Unit with Large Board Capability



Model 850 measures less than 28" x 22" x 17" (695 x 540 x 410 mm) yet reflows both SnPb and lead-free PCB assemblies up to 13" x 9.4" (330 x 240 mm) using forced hot air convection.

Warm-up time is quick in this compact oven, only 90°C/min.

850 Reflow Oven Key Features

- Bench-top, batch processing of PCBs up to 13" (330 mm) x 9.4" (240 mm)
- High-efficiency, forced hot air heating system with stable, well-balanced heat transfer and low turbulence
- Upper and lower resistance heaters with PID temperature control
- Simple operation with preheat- and reflow-phase time and temperature parameter settings via LCD touchscreen display
- 'Hot Bake' function for pre-reflow drying of fine-pitch devices and other components susceptible to humidity absorption
- Audible alarms for completion of soldering cycle, system status, and high oxygen level
- Quick start-up; low power consumption

850 Batch Convection Reflow Oven - Specifications	
Applicable Solder Types	Lead-Free and Leaded
PCB Size (Max.)	13" (330 mm) x 9.4" (240 mm)
Heating Method	Forced Hot Air Convection; Resistance Heaters
Min / Max Temperatures	Preheat stage: 50°C/230°C Reflow stage: 60°C/260°C
Temperature Control Method	PID Control; ±1.5%
Warm-up Time	90°C/min
Programming	LCD Touchscreen
Power	220 V, Single Phase, 50/60 Hz 1.5 KW; 4 KW (max.)
Air Supply	60 psi (4 bar)
Dimensions	27.4" L x 21.2" W x 16.1" H (695 mm L x 540 mm W x 410 mm H)
Weight	approx. 55 lbs. (25 Kg)

850 Batch Reflow Oven Includes:

- Batch reflow system for SnPb and lead-free solders
- Forced hot air convection
- PID control with $\pm 1.5^{\circ}\text{C}$ accuracy
- Board capacity to 330 x 240 mm (13" x 9.4")
- LCD touchscreen control panel for setting preheat and reflow time and temperature parameters
- Large double-pane glass viewing window
- Built-in thermocouple for monitoring
- Audible alarms for completion of soldering cycle, system status and high oxygen level
- Power requirement: 220V, single phase, 50/60Hz